

Title of Invention

POLISHING PAD WITH ADJUSTED CROSSLINKING DEGREE AND PROCESS FOR PREPARING THE SAME

5

Abstract

The polishing pad according to an embodiment comprises a multifunctional low-molecular-weight compound as one of the polymerization units of the polyurethane-based resin that constitutes the polishing layer, thereby reducing the unreacted diisocyanate monomer in the production process to enhance the processability and quality and to increase the crosslinking density. Thus, the polishing pad may be applied to a process of preparing a semiconductor device, which comprises a CMP process, to provide a semiconductor device such as a wafer of excellent quality.

15

Fig. 1